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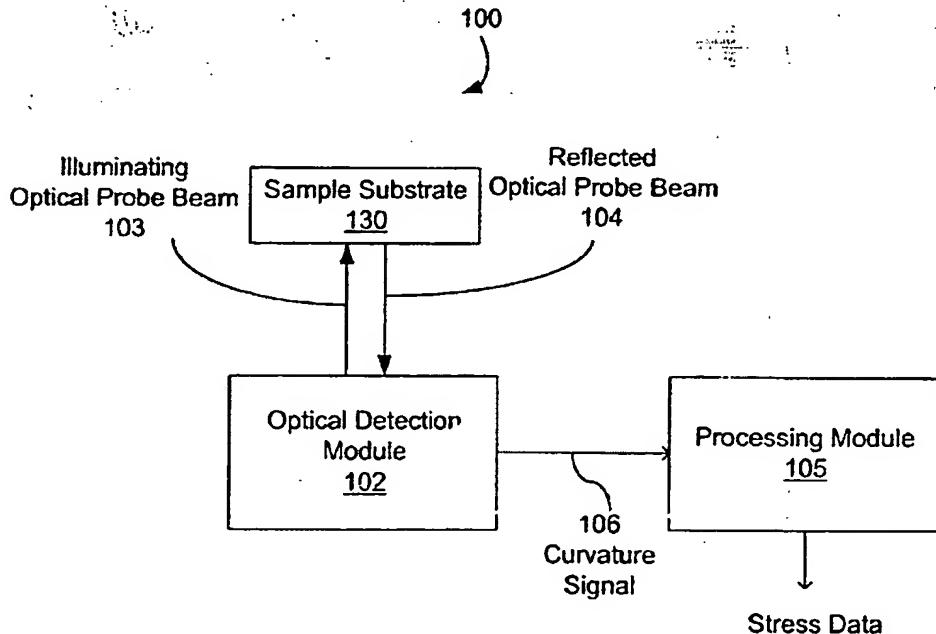
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(54) Title: REAL-TIME EVALUATION OF STRESS FIELDS AND PROPERTIES IN LINE FEATURES FORMED ON SUBSTRATES



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(57) Abstract: Methods and systems for evaluating stresses in line features formed on substrates. Stresses may be computed from measured curvature information based on simple analytical functions. The curvature information can be obtained optically by, e.g., a coherent gradient sensing method, to obtain a full-field measurement of an illuminated area.



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**REAL-TIME EVALUATION OF STRESS FIELDS AND PROPERTIES  
IN LINE FEATURES FORMED ON SUBSTRATES**

This application claims the benefit of U.S. Utility

5 Application No. 09/560,719 filed on April 27, 2000.

**BACKGROUND**

This application relates to evaluation of stress fields and properties in line features formed on substrates.

10 Measurements of various properties of a substrate and features fabricated on the substrate may have important applications. For example, manufacturing of certain devices requires fabrication of various features and components on a substrate (e.g., a semiconductor or a  
15 glass substrate). Such substrate-based integrated devices include, among others, integrated electronic circuits where micro circuit components are formed on a semiconductor substrate, integrated optical devices where micro optical components are fabricated on a substrate,  
20 micro-electro-mechanical systems where micro actuators and other mechanical components are fabricated on a semiconductor substrate, flat panel display systems where light-emitting elements, thin-film transistors and other elements are fabricated on a transparent substrate (e.g.,

elements are fabricated on a transparent substrate (e.g., a glass), or a combination of two or more of the above devices.

Different materials and different structures are  
5 usually formed on the substrate and are in contact with  
one another. Some devices may also use complex  
multilayer geometry. Hence, the interfacing of different  
materials and different structures may cause a complex  
stress state in each feature due to differences in the  
10 material properties and the structure properties at  
interconnections under different fabrication processes  
and environmental factors (e.g., variations or  
fluctuations in temperature). In fabrication of an  
integrated circuit, for example, the stress state of the  
15 interconnect conducting lines may be affected by film  
deposition, rapid thermal etching, chemical-mechanical  
polishing, and passivation during the fabrication  
process.

It is desirable to measure stresses on various  
20 features formed on the substrate to improve the design of  
the device structure, selection of materials, fabrication  
process, and other aspects of the devices so that the  
performance and reliability of the device can be  
enhanced. The stress measurements may be used to assess

or evaluate the reliability of materials against failure from such phenomena as electromigration, stress-voiding and hillock formation. The stress measurements may also be used to facilitate quality control of the mechanical 5 integrity and electromechanical functioning of circuit chip dies during large scale production in wafer fabrication facilities. In addition, the stress measurements may be used to improve the design of various thermal treatments (such as temperature excursions during 10 passivation) and chemical and mechanical treatments (such as polishing) to reduce their contribution to the residual stresses in the final device.

#### SUMMARY

15 A system according to one embodiment of the invention includes an optical detection module to obtain surface curvature information of a substrate-based device which has line features formed on a substrate, and a processing module to produce stress information of the 20 line features based on the curvature information. The optical detection module may include a coherent gradient sensing system to measure the surface gradient of a surface based on phase information in the wavefront of a reflected optical probe beam.

One method according to one embodiment includes first measuring a first curvature of a substrate at a location and along a longitudinal direction of a line feature formed at the location on the substrate and then

5 measuring a second curvature of the substrate at the same location along a transverse direction perpendicular to the longitudinal direction. Next, an analytical function is used to compute stresses on the line feature based on measured first and second curvatures.

10 Alternatively, stresses of a line feature may be determined before the line feature is formed. In this method, curvatures of a substrate are measured before a film is deposited. Then the film is deposited on the substrate and its curvature is measured. Next, the

15 stress information of the deposited film is obtained and is used to determine stresses on a line feature to be patterned from the film based on an analytical function. This method can be extended to structures where line features are formed over two or more underlying films on

20 the substrate.

Another method determines stress information of line features embedded in trenches of a layer formed on a substrate. The curvatures of the embedded line features are measured by using an optical probe beam to obtain

curvature map of the illuminated area based on spatial gradient information in the reflected optical beam. Then measured curvatures are compared to curvatures of the line features computed from an analytical function. The 5 deviation is then used to determine presence of residual stresses.

Yet another method measures curvatures of a line feature and a film from which the line feature is formed as a function of temperature to determine yield 10 temperatures at which the line and the film change their curvature dependence of the temperature from a linear manner to a nonlinear manner. The ratio between a yield stress of the line feature and a yield stress of the film at their respective yield temperatures can then be 15 determined from an analytical function.

These and other features, and associated advantages of will be apparent from the description and drawings, and from the claims.

#### DESCRIPTION OF DRAWINGS

20 FIG. 1 is a block diagram of a stress measurement system according to one embodiment of the invention.

FIG. 2 illustrates one embodiment of a coherent gradient sensing system.

FIG. 3 shows a coherent gradient sensing system having two independent optical arms to obtain simultaneously spatial shearing in two different directions.

5 FIG. 4A illustrates a top view of an exemplary structure of a thermoelastic model according to one embodiment of the invention.

FIG. 4B illustrates a cross-sectional view of the structure shown in FIG. 4A.

10 FIGS. 5 and 6 are flowcharts showing two methods of determining stresses of line features based on optical full-field surface curvature measurements.

FIG. 7 illustrates two exemplary subdivision areas of patterned line features on a substrate.

15 FIGS. 8A and 8B illustrate a model for line features embedded in a layer on a substrate and a model for line features embedded in a layer on a substrate and capped with a passivation layer.

FIG. 9 shows a flowchart for using the system shown  
20 in FIG. 1 to measure curvatures of line features embedded in a layer on the substrate.

DETAILED DESCRIPTION

The methods and systems of this application include at least an optical detection mechanism to measure curvature parameters of line features formed on a substrate and a processing mechanism to extract stress information of the line features from the measured curvature parameters. The optical detection mechanism may provide a full-field measuring capability to simultaneously measure curvatures of one or more areas where line features are located, without the conventional point-to-point scanning measurement. The processing mechanism may use only the curvature information to directly compute the stresses based on an analytical formulation to eliminate complex numerical computation.

Hence, the stress information can be obtained within a short processing time. This combination of the full-field optical detection and the processing can produce a spatial map of the stress distribution in the area under measurement in virtually real time so long as the change in the stress is slower than the processing time.

FIG. 1 shows a stress measurement system 100 according to one embodiment which includes an optical detection module 102 to implement the optical detection mechanism and a data processing module 105 to implement

the processing mechanism. The optical detection module 102 produces an illumination optical beam 103 to a surface of the sample substrate 130 and then detects the reflected beam 104. The illumination beam 103 is 5 directed so as to illuminate an area which includes one or more areas having line features under measurement. The reflected beam 104 from the sample substrate 130 is then optically processed to produce an optical pattern that has the curvature information of the entire 10 illuminated area. This optical pattern is converted into a curvature signal 106. The signal is sent to the processing module 105 which may include an electronic processor or other type of processor. The curvature signal 106 may be an electronic signal representing the 15 optical pattern. The signal is then processed to produce curvature data for the entire illuminated area on the substrate 130. The processing module 105 produces desired stress data on line features formed on any one or more desired locations in the illuminated area on the 20 substrate 130 based on respective curvature data.

FIG. 2 shows one embodiment of a coherent gradient sensing ("CGS") system 200 as an implementation of the optical detection module 102. See, U.S. Patent No. 6,031,611 to Rosakis et al. The CGS system 200 uses a

collimated coherent optical beam 112 from a light source 110 as an optical probe to obtain curvature information indicative of a specularly reflective surface 130 formed of essentially any material. An optical element 120 such 5 as a beam splitter can be used to direct the beam 112 to the surface 130. When the reflective surface 130 is curved, the wavefront of the reflected probe beam 132 is distorted and thereby the reflected probe beam 132 acquires an optical path difference or phase change 10 associated with the curvature of the surface 130 under measurement. This system produces a "snapshot" of each point within the illuminated area on the surface 130 and hence the curvature information at any point along any direction within the illuminated area can be obtained. 15 This can eliminate the need for measuring one point at a time in a sequential manner by using a scanning system.

Two gratings 140 and 150 spaced from each other are placed in the path of the reflected probe beam 132 to manipulate the distorted wavefront for curvature 20 measurement. Two diffraction components produced by the second grating 150 diffracting two different diffraction components produced by the first grating 140 are combined, by using an optical element 160 such as a lens, to interfere with each other. The diffraction by the two

gratings 140 and 150 effectuates a relative spatial displacement, i.e., a phase shift, between the two selected diffraction components. This phase shift is a function of the spacing between the two gratings 140 and 5 150 when other grating parameters are fixed. A spatial filter 170 is placed relative to the optical element 160 to transmit the interference pattern of the selected diffraction components and to block other diffraction orders from the second grating 150.

10 The transmitted interference pattern is then captured by an imaging sensor 180 which may include an array of sensing pixels, such as a CCD array, to produce an electrical signal representing the interference pattern. A signal processor 190, which may be part of 15 the processing module 105 in FIG. 1, processes the electrical signal to extract a spatial gradient of the phase distortion caused by the curvature of the reflective surface 130. This spatial gradient, in turn, can be further processed to obtain the curvature 20 information and hence a curvature map of the illuminated area on the surface 130 can be obtained. A single spatial differentiation is performed on the interference pattern to measure the surface gradient. This technique can provide accurate measurements of surface curvatures

when the curvature variation of the surface is gradual, i.e., when the out-of-plane displacement is less than the thickness of the film, the line or the substrate. This technique is insensitive to rigid body motion in

5 comparison with some other interferometric techniques. Details of this data processing operation are described in the above-referenced U.S. Patent No. 6,031,611 to Rosakis et al.

The two gratings 140 and 150 in general may be any

10 gratings, with different grating periods and oriented with respect to each other at any angle. Preferably, the two gratings may be oriented with respect to each other in the same direction and may have the same grating periods to simplify the data processing. In this case,

15 the grating direction is essentially set by the direction of the relative spatial displacement ("shearing") between the two selected diffraction components due to the double diffractions by the gratings 140 and 150.

Certain applications may require spatial shearing in

20 two different directions to obtain a full-field two-dimensional curvature measurement. This may be done by using the CGS system 200 to perform a first measurement when the sample surface 130 is at a first orientation and subsequently to perform a second measurement when the

sample surface 130 is rotated to a second orientation (e.g., perpendicular to the first orientation).

Alternatively, a two-arm CGS system, shown in FIG. 3 may be implemented to have two separate sets of double 5 gratings in two different directions to simultaneously produce the interference pattern in two different spatial shearing directions. Hence, time-varying effects in the curvature distribution in both spatial shearing directions can be obtained.

10 The above CGS systems may be used to measure curvatures of various features and components formed on a substrate either directly or indirectly. In the direct measurement, the probe beam in the CGS can be directly sent to the top surface of these devices to obtain the 15 curvature information. This usually requires that the surface features and components and their surrounding areas are preferably smooth and optically reflective. In addition, it is desirable that properties of the features and components and their surrounding areas other than 20 their curvatures do not significantly contribute to the wavefront distortion. Hence, the wavefront distortion can be used as an indicator of the curvatures of the area illuminated by optical probe beam. For example, some completed integrated circuits have a top passivation

layer, usually made of a non-conductive dielectric material, over the circuit elements on the substrate to protect the underlying circuits. The surface of the passivation layer is in general smooth and is 5 sufficiently reflective for CGS measurements.

However, the above conditions may not be met in some other substrate-based devices. For example, features and components formed on the front side of a substrate or their surrounding areas may not be optically reflective.

10 The features and components on the front side may distort the reflected wavefront due to factors other than the curvatures, such as the height of a feature or component being different from its surrounding areas. In these cases, the curvatures of the features or components may 15 be indirectly measured by inference from the curvature measurements of the corresponding locations on the opposite surface on the back side of the substrate. This is possible because the stresses in the non-continuous features and components formed on the substrate can cause 20 the substrate to deform and the thin films formed over the substrate generally conform to the substrate surface.

When the heights of certain features are different from their surroundings, the phase distortion on the wavefront of the reflected probe beam for each feature

includes at least the portion contributed from the height difference and the portion contributed from the curvatures. In addition to using the back side of the substrate for the CGS measurement, the CGS measurement

5 may also be performed by illuminating the front side. The curvature information can thus be extracted by removing the effects of the height difference in computation of the curvatures if the height information is known.

10 In addition to curvature measurements of a completed substrate-based device, the CGS technique can also be used to perform in-situ curvature measurements of a substrate and each layer or feature during each fabrication step of a substrate-based device. The CGS

15 technique can achieve this due to its full-field capability of simultaneously measuring the curvatures of all locations within an illuminated area. Therefore, each measurement can be performed and completed in a short time without interrupting the fabrication sequence.

20 Because the CGS technique uses an optical probe beam as the probe to obtain the curvature information, the measurement is non-invasive and hence does not interfere with the fabrication process when the intensity of the optical probe beam is properly kept below an acceptable

level. In addition, the optical probe beam and its reflected beam from the substrate can be conveniently guided to and from the substrate in a processing chamber through one or more optical windows in the processing 5 chamber.

Therefore, during the fabrication of the thin-film layers and various features in each layer, the curvatures and associated stresses of each layer and each feature formed in each layer may be monitored with the CGS 10 technique. This in-situ stress monitoring mechanism may be applied to various aspects of the substrate fabrication.

For example, this in-situ stress monitoring mechanism may be used to screen out a defective batch of 15 processed substrates at any intermediate stage during the fabrication prior to completion of the entire fabrication processes. It is known that fabrication process and associated thermal cycling can introduce stresses in fabricated features. For example, the various 20 metallization processes are carried out at elevated temperatures. Also, the layers may exhibit different mechanical, physical and thermal properties which can lead to high stresses in interconnection structures due to, e.g., mismatch in the amounts of thermal expansion

and contraction between dissimilar materials. These stresses can cause, among others, undesired stress-induced voiding and interfacial cracking, and can contribute to electromigration. In addition, the 5 stresses may cause cracking of the substrate. Voiding, electromigration, and substrate cracking are among the leading failure factors in integrated circuits.

Some of the defects are caused by stresses after an intermediate step during the fabrication. A device is 10 defective when the stresses at various parts exceed predetermined acceptable values. The above in-situ stress monitoring can be used to measure the stresses at selected stages or continuously during the fabrication. The measured stresses are compared to the acceptable 15 values. If a measured stress is greater than its acceptable value, a defect is discovered. The fabrication process may be terminated since the final device would be defective. Thus, the remaining fabrication steps need not be carried out. This avoids 20 the wasteful and inefficient practice in some conventional fabrication methods where the defects of the fabricated devices are tested only after the entire fabrication processes are completed.

Another exemplary application of this in-situ stress monitoring mechanism is adjustment and optimization of the processing parameters and conditions in fabrication to reduce the stresses in the substrates. Because the 5 CGS technique can be used to monitor the stresses in situ during the fabrication, contributions to the stresses from different processing steps can be identified by monitoring the stresses at each processing step. In addition, the processing parameters (e.g., temperature, 10 duration or duty cycle) of each processing step may be adjusted either independently or in reference with the processing parameters of other processing steps to reduce the stresses. Effects on the stresses may be measured by the CGS technique upon each adjustment so that a relation 15 between the parameter and the stresses can be established. The steps of adjusting a processing parameter and measuring the resultant stresses may be carried out in an iteration process until the resultant stresses are reduced to satisfactory levels. Hence, the 20 processing steps can be controlled to increase the overall yield of the fabrication.

Yet another application of the CGS technique is to monitor large surface deformation which has an out-of-plane displacement greater than the thickness of the line

and the substrate. Although the accuracy of the CGS measurements deteriorates if the surface deformation is no longer small compared to thickness of the line and the substrate, this deviation of the CGS measurements from 5 predicted curvature values may be used as an indicator of presence of uniform, large surface deformations if the CGS system is used for in-situ monitoring.

Referring back to FIG. 1, after the curvature map is obtained, the processing module 106 then processes the 10 curvature map to produce a corresponding stress map of the illuminated area on the sample surface. This is an important aspect of the system 100 shown in FIG. 1 and is accomplished by using a simple analytical formulation to compute the stresses on a feature from the curvature data 15 and the material parameters of the substrate and the feature material.

In one implementation, the processing is based on a thermoelastic model for thin periodic line features formed on a thick substrate as described below. Certain 20 aspects of the thermoelastic model, including detailed calculation steps, are disclosed by Wikstrom, Gudmundson, and Suresh, in "Thermoelastic Analysis of Periodic Thin Lines Deposited on A Substrate," Journal of the Mechanics

and Physics of Solids, vol. 47, pp. 1113-1130 (May, 1999).

FIGS. 4A and 4B schematically illustrate the structure of the thermoelastic model according to one embodiment. Multiple identical line features 402 are formed on a surface of a substrate 400. The line features 402 each have a width  $b$  and a thickness or height  $t$  and are evenly spaced from one another by a spacing  $d$  to form a periodic pattern. It is assumed that the dimension of the substrate 400 (e.g., diameter) is much greater than the thickness,  $h$ , of the substrate 400. For example, it may be sufficient for practical purposes that is at least 10 times, or preferably 50 times, greater than  $h$  in some devices. It is also assumed that both the thickness,  $t$ , and the width,  $b$ , of each line feature 402 are much less than the longitudinal length  $l$  and the thickness  $h$  of the substrate 400, by at least a factor of 10, for example, 25 or greater. The accuracy of the model depends on these assumptions: the accuracy generally increases as these factors increase. Under these assumptions, the substrate 400 may be treated as a homogenized anisotropic plate.

A Cartesian coordinate system ( $x_1, x_2, x_3$ ) is established in FIGS. 4A and 4B for the thermoelastic

model. The directions marked  $x_1$  and  $x_2$  represent the directions along and across the line features, respectively, in the plane of the substrate 400. The direction marked  $x_3$  represents the direction normal to the 5 plane of the substrate 400. The volume average value of any quantity A over some volume V is defined as

$$\bar{A} = \frac{1}{V} \int A(x_1, x_2, x_3) dV.$$

10 Based on the analysis by Wikstrom et al., supra., the volume-averaged stresses in each line feature 402 can be expressed in terms of the curvature  $k_1$  along the  $x_1$  direction (i.e., longitudinal), the curvature  $k_2$  along the  $x_2$  direction (i.e., transverse) of the substrate 400:

15

$$\begin{bmatrix} \bar{\sigma}_{11} \\ \bar{\sigma}_{22} \\ \bar{\sigma}_{33} \end{bmatrix} = \frac{-E_s}{6(1-v_s^2)} \frac{h^2}{t} \frac{d}{b} \begin{bmatrix} 1 & v_s & 0 \\ v_s & 1 & 0 \\ 0 & 0 & \frac{1-v_s}{2} \end{bmatrix} \begin{bmatrix} k_1 \\ k_2 \\ 0 \end{bmatrix}, \quad (1)$$

where  $\sigma_{\alpha\beta}$  represents the stress tensor components ( $\alpha, \beta=1, 2$ ), and  $E_s$  are  $v_s$  are Young's modulus and Poisson's ratio 20 of the substrate 400, respectively. The volume average of the shear stress  $\sigma_{12}$  is zero in this case. The

negative sign “-” in Equation (1) is used to implement an elected sign convention, i.e., a positive value represents one direction of the curvature while the negative value represents the opposite direction of 5 curvature. Notably, each stress component is a linear sum given by  $f_1(E_s, v_s, h, t, d, b) \cdot k_1 + f_2(E_s, v_s, h, t, d, b) \cdot k_2$ , where coefficients  $f_1$  and  $f_2$  are functions of  $E_s$ ,  $v_s$ ,  $h$ ,  $t$ ,  $d$ , and  $b$ . Therefore, the stresses of each line feature can be computed based on elastic properties of the 10 substrate and the geometry of the line features.

Hence, measurements of curvatures of the substrate 400 at each line feature 402 allow determination of volume-averaged elastic stresses by a simple analytical function based on dimension parameters of the substrate 15 400 and each line feature 402, the elastic properties of the substrate 400 (e.g., Young's modulus and Poisson's ratio). One of the features of this method is that the stress computation of Equation (1) does not require any detailed information on the material composition, the 20 mechanical and other properties of the line feature itself. Although these characteristics of the line feature are among the primary factors that determine the stress behaviors of the line feature, the effects of

these characteristics are included in the measured curvatures along and cross the line feature,  $k_1$  and  $k_2$ .

Another feature of this method is that Equation (1) is a simple analytical formula and hence the stress computation based on the measured curvatures  $k_1$  and  $k_2$  can be carried out by a processor in a short time. For example, a microprocessor can be used to implement a computer routine to carry out the computation shown in Equation (1). Hence, complex and time-consuming numerical computations are essentially avoided. In addition, the simple analytical formula in Equation (1) has been shown to be accurate in comparison with complex numerical computations based on finite element analysis (Wikstrom et al., *supra*). This feature of the data processing module, when combined with the full-field parallel processing of the CGS optical detection module, allows the stress measurement system 100 of FIG. 1 to measure the curvatures of a location and generate the respective stresses at a relatively high speed.

Therefore, the system 100 may be used to measure temporal changes of curvatures and associated stresses of a line feature in real time for many processes of semiconductor fabrication.

The above stress computation method with respect to Equation (1) provides a way of obtaining stress data of a line feature on a substrate if the information on a thin film from which the line feature is formed is not 5 available. An example of this situation is to determine the stresses in a device after the line feature is formed from a thin film such as a completed IC circuit.

FIG. 5 shows a flowchart of the above stress measurement method based on Equation (1). Such stress 10 measurement can be performed either after the fabrication of the substrate is completed or during the fabrication. as an in-situ monitoring mechanism.

An alternative method of the present application can be used to determine the stresses of line features 15 patterned from a thin film on a substrate even before the line features are formed if the curvatures of the substrate and the thin film can be measured prior to patterning. One example of this situation is in-situ measurements during the fabrication by using the 20 curvature measurement system 100 shown in FIG. 1.

First, before any layer is formed over the substrate, the curvature map of the bare substrate is measured (so is the associated stress map). When the substrate and the subsequent deposited continuous film

thereon are essentially isotropic, the curvature at any location should be identical along any direction. Next, after a thin film is deposited on the substrate, the curvature map of the continuous film is measured. The 5 stress in the unpatterned and continuous film at a location of interest can be determined from Stoney's equation:

$$\sigma_{film} = \frac{-E}{6(1-\nu_s)} \frac{h^2}{t} [k_{film} - k_s] \quad (2)$$

10

where  $k_{film}$  and  $k_s$  are the measured curvatures of the deposited film and the bare substrate at the same location of interest, respectively. Here, the sign convention is elected so that the curvature is positive 15 when the substrate surface on which the film is deposited is convex and negative when the surface is concave.

If periodic line features are formed on this film, the curvatures across and along each line feature,  $k_1$  and  $k_2$ , respectively, can be determined from elastic 20 properties of the film and the substrate, and the geometry of the line features by the following analytical formula:

$$\begin{bmatrix} k_1 \\ k_2 \end{bmatrix} = k_{film} \frac{d}{b} \begin{bmatrix} 1 \\ 1 \end{bmatrix} - \frac{\chi}{1-\nu_s} \begin{bmatrix} \nu_{film} - \nu_s \\ 1 - \nu_s \nu_{film} \end{bmatrix}, \quad (3)$$

where  $\nu_{film}$  is the Poisson's ratio of the film,  $\chi$  is given by

5

$$\chi \approx (3.95138) \frac{t}{b} \sum_{j=1}^{10} \frac{d_j}{\left(1 + \frac{t}{b}\right)^j},$$

and coefficient  $d_j$  is given in TABLE 1. Note that when

$\frac{t}{b} \rightarrow 0, \chi \rightarrow 0$  and  $\frac{t}{b} \rightarrow \infty, \chi \rightarrow 1$ . See, Wikstrom et al., supra.

10 Here, it is assumed that the changes in curvatures from  $k_{film}$  to  $k_1$  and  $k_2$  are caused solely from changes in geometry from patterning the film into line features. It also assumed that the elastic properties of the line features are essentially the same as the film.

15

TABLE 1

Coefficients $d_j$	
$j$	$d_j$
1	0.25256
2	0.27079
3	-0.49814
4	8.62962
5	-51.24655
6	180.96305
7	-374.29813
8	449.59474
9	-286.51016
10	73.84223

Accordingly, the volume-averaged elastic stresses on each line feature can be obtained from the following equation:

$$5 \quad \begin{bmatrix} \overline{\sigma_u} \\ \overline{\sigma_z} \\ \overline{\sigma_b} \end{bmatrix} = \sigma_{film} \begin{bmatrix} 1 - \chi v_{film} \\ 1 - \chi \\ \sigma \end{bmatrix}. \quad (4)$$

This method, like the previous method, uses a simple analytical formulation of Equations (2), (3), and (4) to compute the stresses on each line feature. Unlike the 10 previous method, however, the curvature of the substrate required in Equation (2) is measured before the film is deposited while the curvatures  $k_1$  and  $k_2$  of the substrate required in Equation (1) are measured after the line features are formed on the substrate. Hence, this method 15 can be used to predict the stresses of line features to be formed. FIG. 6 shows a flowchart of the stress measurement based on Equation (4).

In addition, the analytical formulation of Equations (2), (3), and (4) can also be applied to lines formed 20 over one or more thin films on the substrate. In this case, the parameter  $k_s$  in Equation (2) is the total curvature of a structure formed by the underlying films and the substrate before the line-forming film is

deposited. This total curvature can be directly measured by using the CGS method. To a first order approximation, the total curvature is the sum of curvatures that would be induced if each individual layer would be deposited by 5 itself on the substrate.

The above stress measurement techniques can be applied to measure a substrate with line features that are oriented in more than one direction, for example, in mutually orthogonal directions. The entire area of 10 interest on the substrate may be divided into two or more subdivision areas depending on the pattern formed thereon so that each subdivision area only has line features that are parallel to one another along one direction. Thus, the model for unidirectional line features as shown in 15 FIGS. 4A and 4B is applicable to each individual subdivision area to compute the corresponding stresses based on the curvature data from the CGS measurement. A non-straight single conductive line hence may include two or more different segments in different subdivision 20 areas. The stresses in this line are obtained by computing stresses in different segments based on the CGS curvature data.

FIG. 9 shows a portion of line features formed on a substrate which includes two subdivision areas A and B.

The directions of line features in each subdivision area are the same. The subdivision areas A and B may be selected in such a way that the distance from the edge in each area to the nearest sharp corner where the lines 5 change direction is at least the greater value of one line width  $b$  or thickness  $t$  of each line feature. This condition can maintain the accuracy of the stress computation based on the model in FIGS. 4A and 4B. The subdivision areas A and B may be measured simultaneously 10 in time by using the system 100 of FIG. 1 when the optical probe beam is directed to illustrate both areas A and B at the same time.

In many practical devices, line features formed over a substrate are often embedded in a different material. 15 For example, conductive lines are often embedded in an insulating conductive material such as an oxide. The model shown in FIGS. 4A and 4B is no longer applicable to the analysis of curvatures and stresses of such structures. In fact, it is difficult to compute stresses 20 in such embedded line features without complex numerical computation. However, a new model can be used to compute curvatures of an embedded line feature based on the structure design, material properties of the embedded line features and the surrounding material.

FIG. 8A illustrates a model for computing curvatures of line features 810 embedded in trenches of a layer 820 formed on a substrate 800. Similar to the model in FIGS. 4A and 4B, the transverse dimension of the substrate 800 5 is assumed to be much greater than its thickness  $h$ . The line features 810 are parallel and are evenly spaced by a spacing  $d$  on the substrate 800 along the  $x_2$  direction. The width  $b$  and the thickness  $t$  of each line feature 810 are also assumed to be much less than its longitudinal 10 length along the  $x_1$  direction and the thickness  $h$  of the substrate 800. See, Park and Suresh, "Effects of Line and Passivation Geometry on Curvature Evolution during Processing and Thermal Cycling in Copper Interconnect Lines," *Acta Materialia* (April, 2000).

15 It is further assumed that, the aspect ratio,  $f_o = t/b$ , of the line features 810 and the aspect ratio of the lines formed in surrounding layer 820,  $f_i = t/(d-b)$ , are comparable to or larger than unity, and that, the 20 curvatures along and across the line features 810 do not influence one another for elastic deformation. According to Park and Suresh, supra., the curvature  $k_1$  of the line features 810 along the line direction  $x_1$  and the curvature  $k_2$  perpendicular to the line direction  $x_1$  caused by a

change in temperature  $\Delta T$  within the elastic range can be expressed as

$$k_1 = \frac{6}{E} \frac{t}{h^2} E_1 (\alpha_1 - \alpha_s) \Delta T,$$

5 (5)

$$k_2 = \frac{6}{E} \frac{t}{h^2} E_2 (\alpha_2 - \alpha_s) \Delta T,$$

(6)

where

$$10 \quad E_1 = f_l E_l + f_o E_o = \frac{b}{d} E_l + (1 - \frac{b}{d}),$$

(7)

$$E_2 = \frac{E_l E_o}{f_l E_o + f_o E_l},$$

(8)

15

$$\alpha_1 = \frac{f_l E_l \alpha_l + f_o E_o \alpha_o}{f_l E_l + f_o E_o},$$

(9)

$$\alpha_2 = f_l \alpha_l + f_o \alpha_o + \frac{f_l f_o (v_l E_o - v_o E_l) (\alpha_l - \alpha_o)}{f_l E_l + f_o E_o}$$

20 (10)

and  $E_1$ ,  $v_1$ , and  $\alpha_1$  are Young's moduli, Poisson's ratio, and coefficient of thermal expansion for the line features 810, respectively, and  $E_0$ ,  $v_0$ ,  $\alpha_0$  are Young's 5 moduli, Poisson's ratio, and coefficient of thermal expansion for the layer 820, respectively. In the composite analogy, the layer comprising the line features 810 (e.g., Cu lines) and the surrounding layer 820 (an oxide such as silicon dioxide) is homogenized as an 10 anisotropic composite layer with Young's moduli  $E_1$  and  $E_2$  along and across the line direction, respectively, and with thermal expansion coefficients,  $\alpha_1$  and  $\alpha_2$ , along and across the line direction, respectively.

The predictions of this simple analytical analysis 15 have been shown to be reasonably close to the results of more detailed finite element simulations, with a deviation from about 3% to about 17%. For some practical configurations of Cu lines in oxide trenches, the error is typically smaller than 17%.

20 FIG. 8B shows another model where a capping passivation layer 830 is formed over the line features 810 and the layer 820. Assuming the passivation layer 830 is much thinner than the substrate 800, the curvatures of the passivated line features 810, due to

elastic deformation caused by a change  $\Delta T$  in temperature, can be expressed as

$$k_1^{\text{pass}} = \frac{6}{E_s} \frac{t}{h^2} E_1 (\alpha_1 - \alpha_s) \Delta T + 6 \frac{h_p}{h^2} \cdot \frac{E_p}{E_s} \cdot \frac{(1-\nu_s)}{(1-\nu_p)} (\alpha_p - \alpha_s) \Delta T,$$

5 (11)

$$k_2^{\text{pass}} = \frac{6}{E_s} \frac{t}{h^2} E_2 (\alpha_2 - \alpha_s) \Delta T + 6 \frac{h_p}{h^2} \cdot \frac{E_p}{E_s} \cdot \frac{(1-\nu_s)}{(1-\nu_p)} (\alpha_p - \alpha_s) \Delta T,$$

(12)

10 where  $E_p$ ,  $\nu_p$ ,  $\alpha_p$  are Young's modulus, Poisson's ratio, and coefficient of thermal expansion for the passivation layer 830, respectively.

The above models shown in FIGS. 8A and 8B can be used to compute the curvatures of embedded lines on the substrate based on the certain known parameters of the substrate-based devices. Although the stresses of the embedded lines cannot be directly computed from Equations (5)-(12), the models can be implemented in the processing module 105 of the system 100 shown in FIG. 1 to determine 15 whether residual stresses exist in the devices.

20 FIG. 9 shows a flowchart of combining the CGS measurements with the curvature estimation based on the models in FIGS. 8A and 8B to determine the stress

information of the embedded lines. First, the curvatures of embedded lines of a device are measured by the CGS method and computed based on the models in FIGS. 8A and 8B. The CGS measurements provide actual curvatures of 5 the lines while the computed curvatures are only the curvatures caused by elastic deformation. Next, the computed curvatures and the measured curvatures are compared. Their differences indicate the curvatures caused by residual stresses which are not included in the 10 computation. The residual stress should be kept below an acceptable level in order to ensure the normal operation and a desired lifetime of the device. Hence, when the difference either along or cross the line exceeds the acceptable level, the liability or performance of device 15 may be considered as being unacceptable.

The above process can be used to monitor the stresses in the embedded lines during the fabrication process because the CGS is capable of in-situ 20 measurements. The differences in curvatures between the analysis and CGS measurements provide an indication what actually is going on with respect to stress/curvature evolution that is not accounted for in design. Hence, one or more aspects of the fabrication or the design of the devices may be examined and modified to reduce the

residual stresses within the acceptable range. In addition, the in-situ measurements may also be used to terminate the fabrication prior to the completion of the entire process if the residual stresses exceed above the 5 acceptable level at an intermediate step. This monitoring mechanism may reduce the cost and increases fabrication efficiency.

Equations (5), (6) and (11), (12) may also be used to fit measured curvature data to determine a property of 10 the line features or the substrate, such as the Young's modulus, the coefficient of the thermal expansion, and Poisson ratio of the substrate or the line feature. For example, in devices with the passivation layer 830, the CGS measurements of the curvatures may be used to 15 determine properties of the passivation layer 830 based on Equations (11) and (12). The biaxial modulus of the passivation layer 830,  $E_{p,B} = E_p / (1 - \nu_p)$  can be computed from the CGS measurements of  $k_1^{\text{pass}}$  and  $k_2^{\text{pass}}$  that are made during the process before and after the passivation layer 20 is deposited.

The above method for measuring embedded lines can be applied to a new fabrication technique for making copper conductive lines in oxide trenches, "Damascene process." With this technique, trenches are etched in an oxide

layer to conform to the geometry of the copper interconnect lines in the circuit formed on a Si substrate. The etching is performed by using a dry etching process. These oxide trenches are then plugged 5 with Cu with the use of chemical vapor deposition (CVD) or electroplating. The extra copper above the trenches is then removed by chemical-mechanical polishing (CMP), and then a passivation or a capping layer is deposited on top of the interconnect structure.

10 Since the Damascene process involves material removal by polishing, the knowledge of curvature evolution during polishing and subsequent processing is essential on various counts. For example, in-situ monitoring of curvatures using the CGS method can provide 15 information on the "flatness" of the polished surface upon which layers are deposited. This can be an ~~an~~ essential step in quality control. Also, a knowledge of curvature evolution can also give an indication of the evolution of internal stresses during fabrication.

20 Furthermore, the above analysis for unpassivated and passivated lines can also be used to simulate the evolution of elastic stresses during thermal cycling, and can be readily compared with CGS measurements. Examples of such calculations are given in Park and Suresh, and

are verified by comparisons with finite element simulations.

In addition to measuring the stresses caused by elastic changes, the system 100 shown in FIG. 1 may also 5 be configured, based on the model in FIGS. 4A and 4B, to determine some plastic properties of line features formed on a substrate. Line features formed on a substrate may be subject to permanent and plastic deformation under certain thermomechanical treatments. In general, a line 10 feature and the thin film experience elastic deformation when the temperatures are below threshold yield temperatures  $T_1^Y$  and  $T_f^Y$ , respectively. The curvatures of elastic deformation change linearly with the temperatures. When the temperatures are above the 15 threshold yield temperatures  $T_1^Y$  and  $T_f^Y$ , however, plastic deformation occurs and the curvatures change with the temperatures in a nonlinear manner. For example, plastic deformation may occur in conductive lines when heated above the yield temperature during passivation. It is 20 desirable to determine the stresses caused by such plastic deformation.

Suppose that the initial stress-free temperature of a line feature and the continuous film from which the line feature is patterned on the substrate are  $T_1^0$  and  $T_f^0$ ,

respectively. The stress-free temperature ranges of the line/substrate and film/substrate systems can be determined experimentally using the CGS technique to measure the curvatures as a function of temperature. The 5 curvature of the unprocessed continuous film may be determined based on Equation (2) as described above. The temperature change, from the initial stress-free temperature, to initiate plastic yielding in the line and the film, respectively, can be written as:

10

$$\Delta T_e^Y = T_e^Y - T_e^0 = \frac{1-v_f}{E_f(\alpha_s - \alpha_f)} \frac{\sigma_e^Y}{Z^e}, \quad (13)$$

$$\Delta T_f^Y = T_f^Y - T_f^0 = \frac{1-v_f}{E_f(\alpha_s - \alpha_f)} \sigma_f^Y, \quad (14)$$

where  $Z^e$  is given by

15

$$Z^e = \left\{ (1-\chi v_f)^2 - [\chi(1-\chi)(1-v_f)] \right\}^{1/2}. \quad (15)$$

where  $T_e^Y$  and  $T_f^Y$  are temperatures at which permanent, plastic deformation begins to occur in the line feature 20 and the continuous film. At temperatures above  $T_e^Y$  and  $T_f^Y$ , the curvatures of the line and the film begin to change nonlinearly with temperature. Equations (13)-(15)

can be derived based on the model in FIGS. 4A and 4B based on an analysis by Gouldstone, Wikstrom, Gudmundson and Suresh in "Onset of Plastic Yielding in Thin Metal Lines Deposited on Substrates", Scripta Materialia, vol. 5 41, No. 3, pp. 297-304, (August 1999).

From Equations (13) and (14), the following can be obtained

$$\frac{\Delta T_t^Y}{\Delta T_f^Y} = \frac{\sigma_t^Y}{\sigma_f^Y} \frac{1}{Z^e}. \quad (16)$$

10

Because the ratio of the temperature difference can be measured by using the CGS technique and the parameter  $Z^e$  can be calculated based on Equation (4), the ratio of the yield stresses of the line feature and the film can be 15 determined from Equation (16). Thus the CGS method, in conjunction with the above analysis, provides a useful tool for determining the onset of yielding in patterned lines.

The above methods and systems may be used to 20 measure, in real time, the history and spatial variation of stresses on the substrate, line features or films formed thereon. In particular, measurements from the coherent gradient sensing method can be rapidly processed

by analytical computations to obtain spatial and temporal variations of stresses and plastic strains. Information on plastic deformation of the line features and films on the substrate can also be measured.

5 A number of embodiments of the invention have been described. Nevertheless, it will be understood that various modifications and enhancements may be made without departing from the following claims.

WHAT IS CLAIMED IS:

## 1. A system, comprising:

an optical detection module to direct an optical probe beam to a reflective surface of a substrate, which is processed to have line features, to produce a reflected probe beam, said optical detection module operable to produce a curvature signal having curvature information of an area of said reflective surface based on said reflected probe beam; and

10 a processing module to compute stresses of each line feature on said substrate from an analytical function of curvatures in two different directions of the substrate corresponding to the location of the line feature.

15

2. The system as in claim 1, wherein said optical detection module includes first and second gratings in an optical path of said reflected probe beam to produce a phase shift between two diffraction components from said 20 second grating by diffracting two different diffraction components from said first grating.

3. The system as in claim 1, wherein said analytical function includes a linear sum of said curvatures along

said two different directions having coefficients which depend on a thickness, Poisson's ratio and Young's modulus of the substrate, and a dimension of the line feature.

5

4. The system as in claim 1, wherein the line features are formed from patterning a continuous film deposited on the substrate and said analytical function is a function of the stress of the film prior to the patterning, Poisson ratio and thickness of the film, and a dimension of the line feature.

5. The system as in claim 1, wherein said optical detection module projects the optical probe beam to a side of the substrate on which the line features are formed.

6. The system as in claim 1, wherein said optical detection module projects the optical probe beam to a side of the substrate on which the line features are not formed.

7. The system as in claim 1, wherein the line features are formed over at least one film layer on the

substrate, said processing module operable to compute said stresses from a total curvature of the film layer on the substrate prior to formation of the line features.

5        8. The system as in claim 1, wherein said processing module is operable to compute said stresses from a total curvature of the substrate prior to formation of the line features.

10        9. A method, comprising:

      illuminating a substrate with an optical probe beam to generate a reflected probe beam which acquires surface spatial gradient information of an illuminated area on the substrate;

15        processing the surface spatial gradient information in said reflected probe beam to simultaneously measure a first curvature of a substrate at a location and along a longitudinal direction of a line feature formed at the location on the substrate and 20        a second curvature of the substrate at the same location along a transverse direction perpendicular to the longitudinal direction; and

using an analytical function to compute stresses on the line feature based on measured first and second curvatures.

5 10. The method as in claim 9, wherein said analytical function includes a linear sum of the measured first and second curvatures.

11. The method as in claim 10, wherein the linear 10 sum has coefficients which depend on a thickness, Poisson's ratio and Young's modulus of the substrate, and a dimension of the line feature.

12. The method as in claim 9, wherein the line 15 feature includes a first portion along a first line direction and a second portion that is along a second line direction that is different from the first line direction, further comprising measuring the first and second curvatures on the substrate corresponding to a 20 location on the line feature that is spaced by at least a selected distance away from where the line feature changes from the first line direction to the second line direction, wherein the stresses are for the first portion.

13. The method as in claim 12, wherein the selected distance is a greater value of a thickness and linewidth of the line feature.

5

14. The method as in claim 12, further comprising:  
measuring curvatures along and transverse to the line feature in the second portion at a location spaced by at least the selected distance from where the 10 line feature changes from the first line direction to the second line direction; and  
determining stresses on the second portion based on the analytical function.

15. The method as in claim 9, wherein the optical probe beam is directed to a side of the substrate 20 on which the line feature is formed.

16. The method as in claim 9, wherein the optical probe beam is directed to a side of the substrate opposite to the side on which the line feature is formed.

17. The method as in claim 9, wherein the line feature is embedded with a thin film layer deposited on the substrate, further comprising:

computing curvatures of the line feature along  
5 and transverse to the line direction due to an elastic deformation caused by a change in temperature based on an elastic deformation model;

comparing computed curvatures to the measured curvatures to determine curvature differences; and  
10 extracting information about the line feature based on the curvature differences.

18. The method as in claim 17, wherein the computation is performed by using an analytical function.

15

19. The method as in claim 17, wherein the information about the line feature includes information on residual stresses.

20

20. The method as in claim 17, wherein the information about the line feature includes a property of the substrate or the line feature.

21. The method as in claim 20, the property is an elastic property.

22. A method, comprising:

5 illuminating an optical probe beam onto a substrate before a film is deposited to simultaneously measure curvatures of an illuminated area of the substrate based on spatial gradient information in a reflected probe beam;

10 depositing the film on the substrate; illuminating an optical probe beam onto the film to simultaneously measure curvatures of the illuminated area of the film based on spatial gradient information in a reflected probe beam;

15 determining stress information of the deposited film based on measured curvatures of the film and the substrate; and

20 using an analytical function to determine stresses on a line feature to be patterned from the film.

20

23. The method as in claim 22, further comprising:

comparing the measured stresses on the line feature to an acceptable maximum stress; and

terminating further processing of the substrate when a measured stress on the line feature exceeds the acceptable maximum stress.

5        24. The method as in claim 22, wherein the analytical function is a function of the stress information and Poisson ratio of the unpatterned film, and a ratio of a thickness over a linewidth of the line feature.

10       25. The method as in claim 22, wherein measurement of curvatures of the substrate and the film includes obtaining a spatial gradient map of the illuminated area according to phase information in a reflected probe beam 15 from the area.

26. The method as in claim 22, further comprising using first and second gratings spaced in an optical path of the reflected probe beam to cause a phase shift 20 between two diffraction components from the second grating by diffracting two different diffraction components from the first grating.

27. The method as in claim 26, wherein grating directions of the first and second gratings are parallel to each other along a first direction.

5 28. The method as in claim 26, further comprising:  
splitting a portion of the reflected probe beam  
to produce a second reflected probe beam;  
using third and fourth gratings, spaced in an  
optical path of the second reflected probe beam whose  
10 grating directions are parallel along a second direction  
different from the first direction, to produce a phase  
shift; and  
processing phase shifts in the reflected probe  
beam and the second reflected probe beam to produce the  
15 curvatures of the substrate and the film.

29. A method, comprising:

illuminating an optical beam to simultaneously measure curvatures of a film deposited on a substrate at 20 a range of temperatures;

controlling the temperatures so that curvatures of the film change from a linear dependence of the temperature to a nonlinear dependence of the temperature;

determining a film yield temperature at which the linear dependence changes to the nonlinear dependence;

patterning the film to form line features;

5 illuminating the optical beam to simultaneously measure curvatures of a line feature at a range of temperatures;

controlling the temperatures so that curvatures of the line feature change from a linear dependence of 10 the temperature to a nonlinear dependence of the temperature;

determining a line yield temperature at which at which the linear dependence changes to the nonlinear dependence;

15 determining a first temperature difference between the film yield temperature and a film temperature below the film yield temperature;

determining a second temperature difference between the line yield temperature and a line temperature 20 below the line yield temperature;

computing a ratio between a yield stress of the line feature and a yield stress of the film respectively corresponding to the line and film yield temperatures

according to the first and second temperature differences and an analytical function.

30. The method as in claim 29, wherein the  
5 analytical function is a function of Poisson ratio of the film and dimensions of the line feature.

31. The method as in claim 29, wherein the  
curvatures are measured by obtaining spatial gradient  
10 information of the line feature and the film.

32. A method, comprising:

illuminating an optical probe beam onto a substrate on which line features are formed in trenches  
15 of a film to simultaneously measure curvatures of a line feature based on spatial gradient information in a reflected probe beam;

computing curvatures of the line feature from an analytical function based on elastic deformation;

20 comparing computed curvatures to measured curvatures of the line feature to obtain curvature differences; and

determining information about residual stresses in the line feature according to the curvature differences.

5       33. The method as in claim 32, wherein a passivation capping layer is formed over the line features and the film, and wherein the analytical function includes effects of the passivation capping layer.

10       34. The method as in claim 32, further comprising modifying an aspect of a fabrication process or structure design of the line features and the film on the substrate according to the curvature differences.

15       35. The method as in claim 32, wherein the modification is made to set the residual stresses below acceptable values.

36. A method, comprising:

20       illuminating an optical probe beam onto a substrate on which line features are formed, prior to completion of fabrication, to simultaneously measure curvatures of a line feature based on spatial gradient information in a reflected probe beam;

evaluating stresses of the line feature based on the measured curvatures;

performing one or more subsequent fabrication processes when the stresses are below acceptable values;

5 and

terminating fabrication when the stresses exceed the acceptable values.

37. The method as in claim 36, wherein the stresses  
10 are evaluated from an analytical function of curvatures in two different directions of the substrate corresponding to the location of the line feature.

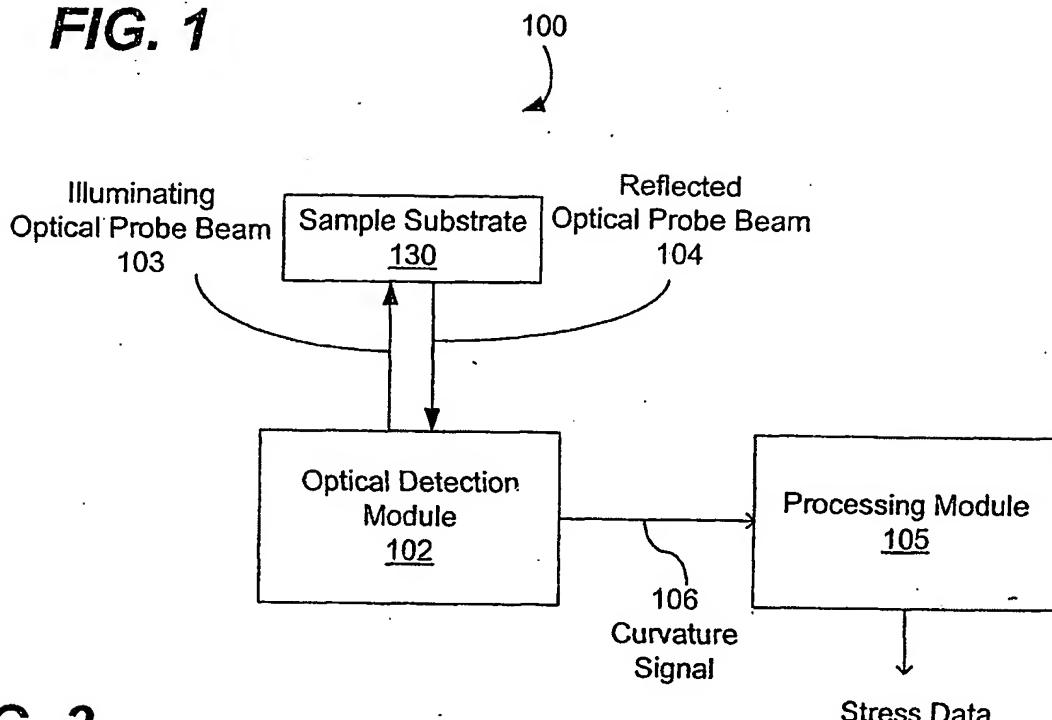
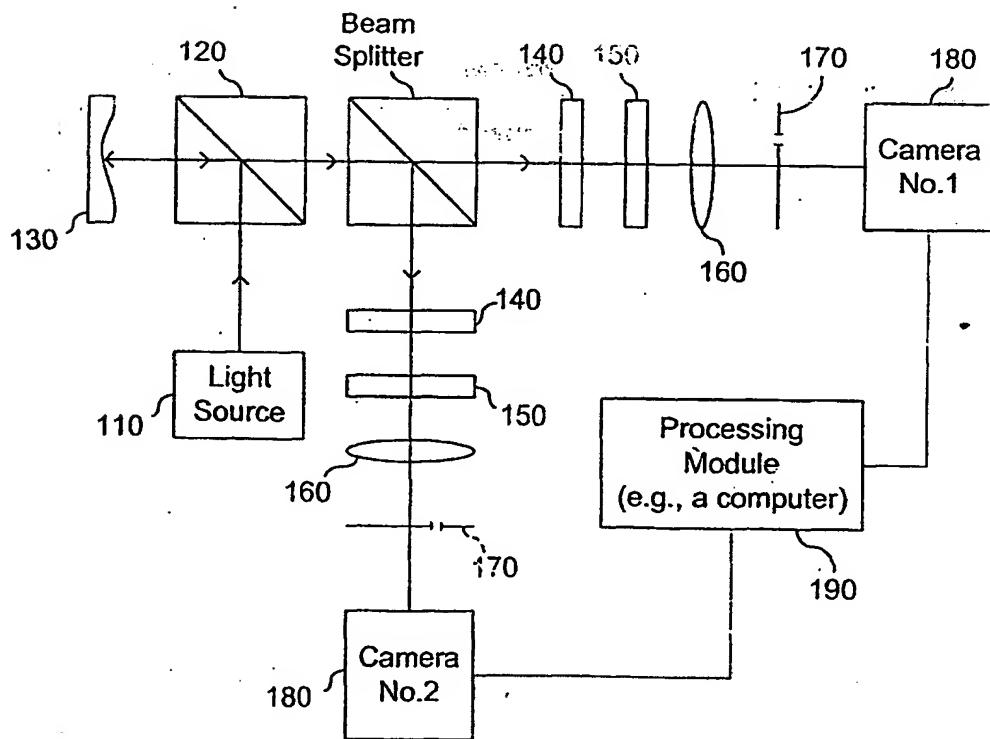
38. A method, comprising:

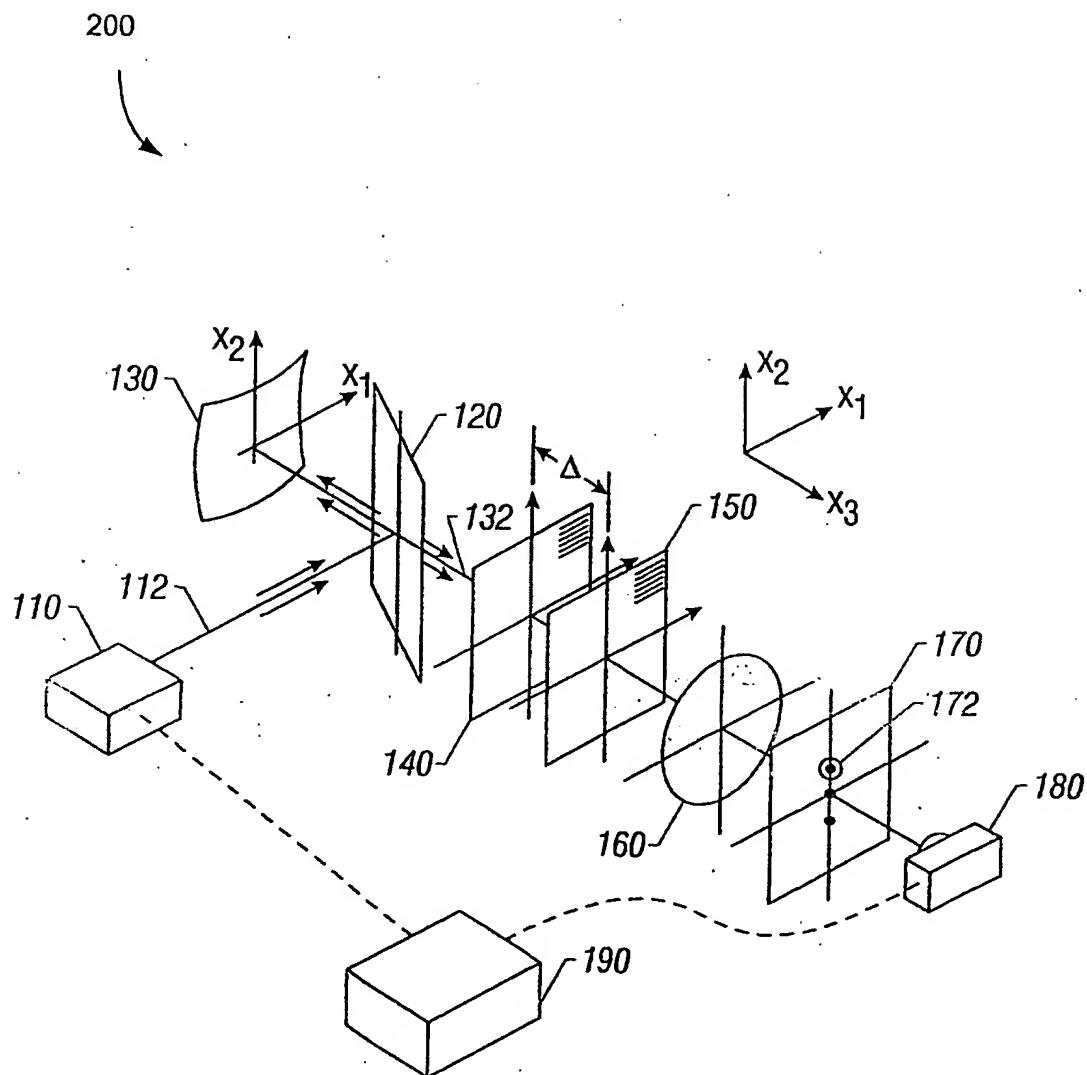
15 illuminating an optical probe beam onto a substrate on which line features are formed, at an intermediate step of fabrication, to simultaneously measure curvatures of a line feature based on spatial gradient information in a reflected probe beam;

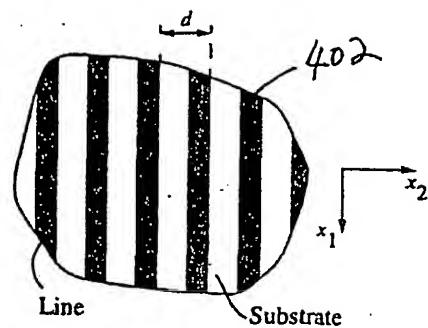
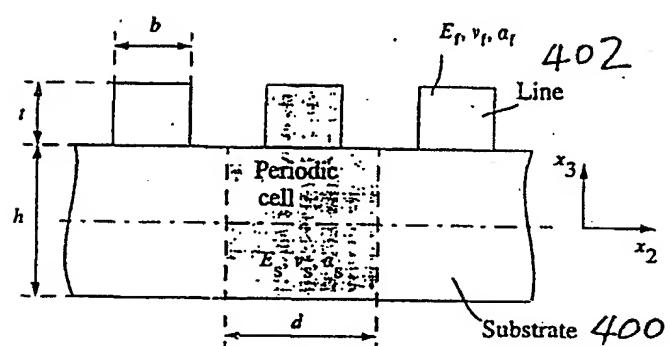
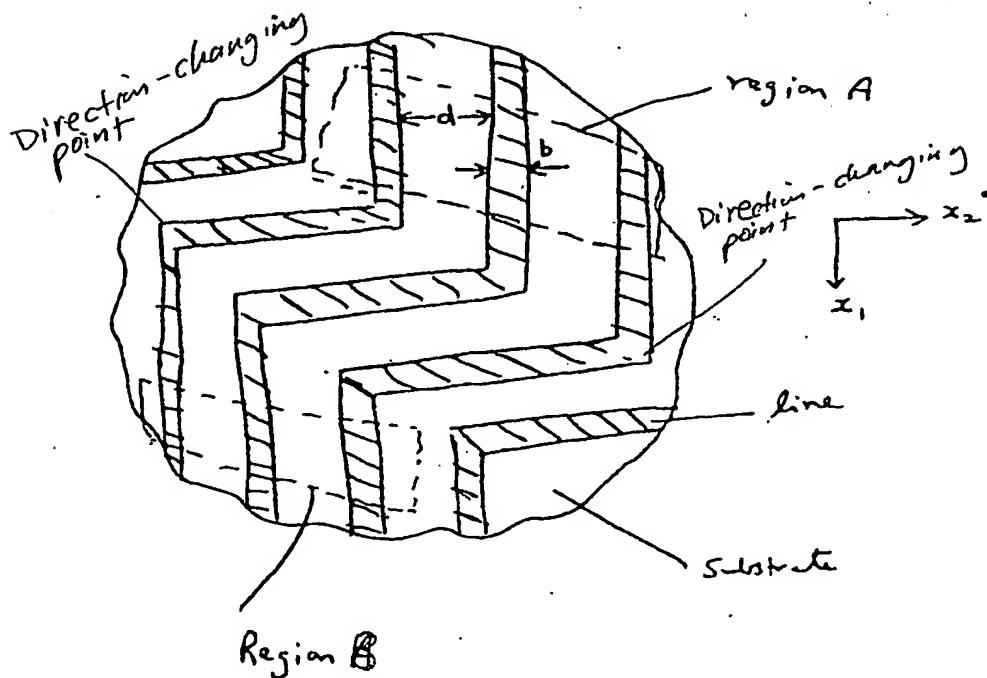
20 evaluating stresses of the line feature based on the measured curvatures; and

adjusting a parameter of fabrication to reduce the stresses below acceptable values.

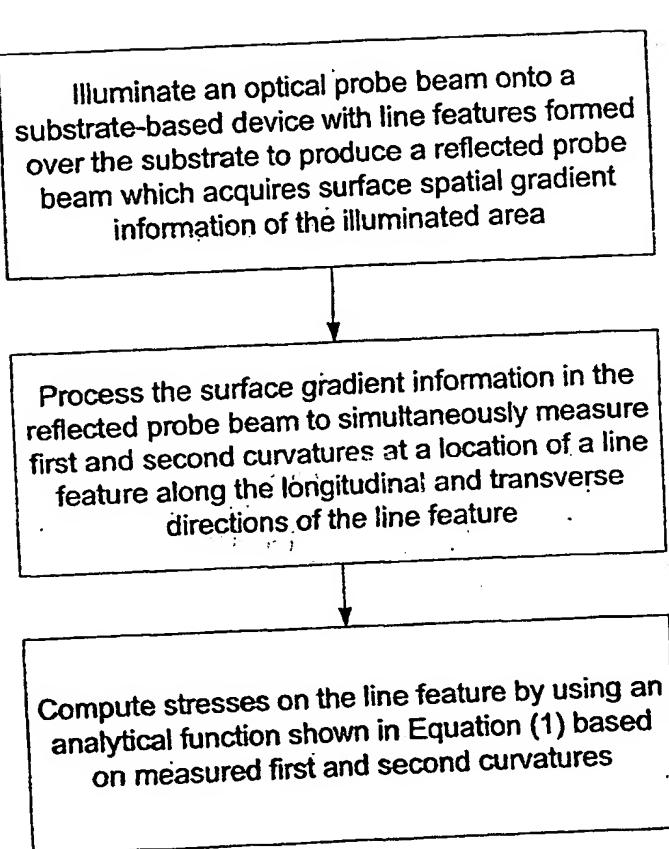
39. The method as in claim 38, wherein the stresses are evaluated from an analytical function of curvatures in two different directions of the substrate corresponding to the location of the line feature.

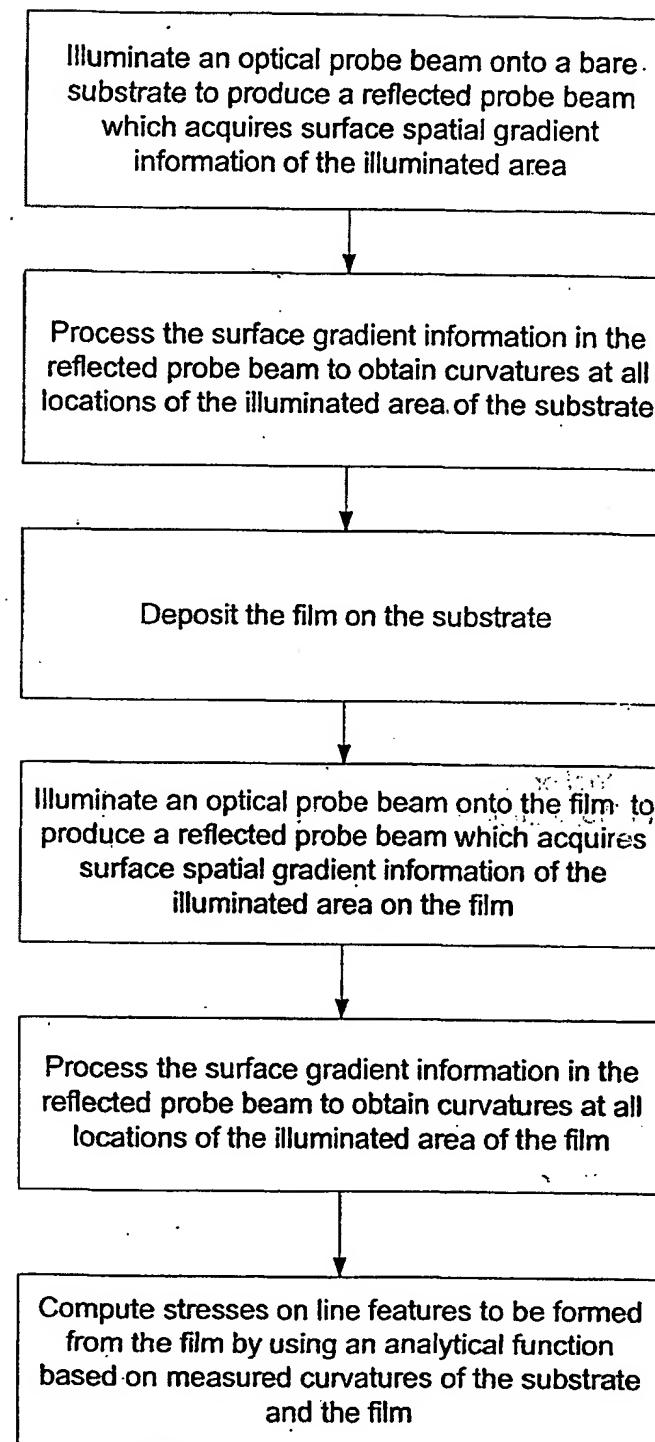
**FIG. 1****FIG. 3**

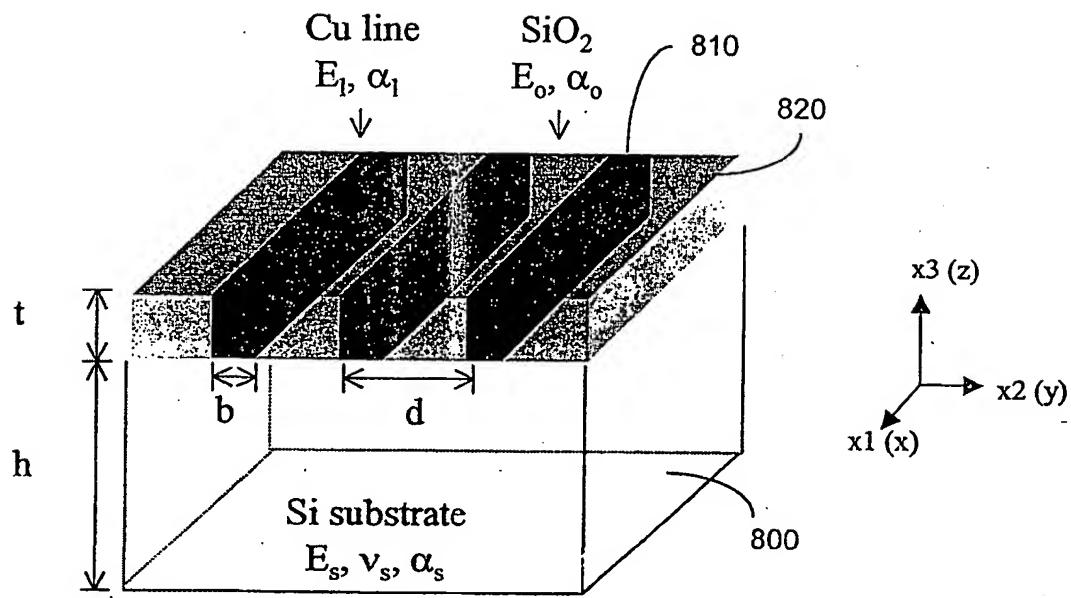
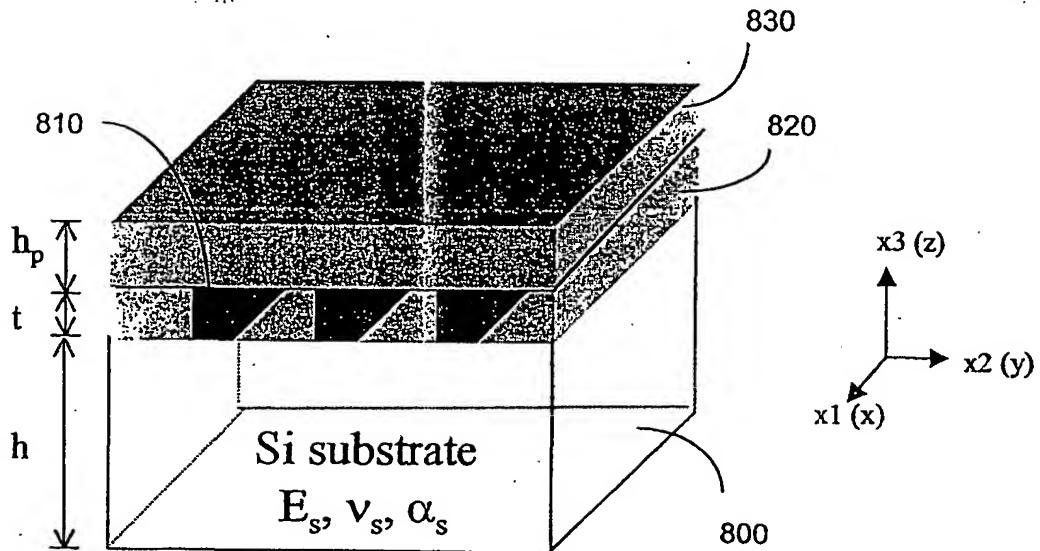
**FIG. 2**

**FIG. 4A****FIG. 4B****FIG. 7**

## FIG. 5



**FIG. 6**

**FIG. 8A****FIG. 8B**

**FIG. 9**